

ABSTRACT

A wafer protective sheet 1 is made of a synthetic resin sheet with a thickness of 80 to 130 μm having a large number of projected parts and recessed parts on its front and rear surfaces. The large number of projected parts and the large number of recessed parts are respectively disposed so that each part is positioned at intersections of lattice stripes, and the projected part and the recessed part are disposed alternately each other. The sheet has such a water-like cross section that the recessed parts in the rear surface match the projected parts on the front surface and the projected parts on the rear surface match the recessed parts in the front surface. The wafer protective sheet 1 has a bending resistance of 30 to 80 mm. The wafer protective sheet 1 of the present invention is sufficiently thin. When the wafer protective sheets are interposed between stacked wafers to protect them, the sheets do not adhere to the wafers. Thus, wafers housed in a container can be protected against vibration during transportation.